



JUNE
2-3
2009

MUNICH, GERMANY

Toshiba support for GSA & IET International Semiconductor Forum includes keynote address and access to ASIC and Foundry specialists

Registration for one-on-one meetings now open

System LSI Division of Toshiba Semiconductor to present vision for future of the ASIC model

Düsseldorf, Germany, 27 April 2009 - Toshiba Electronics Europe (TEE) and parent company Toshiba Semiconductor Company has announced its active support for the GSA & IET International Semiconductor Forum on 2nd and 3rd June 2009. The TEE ASIC and Foundry business unit will be exhibiting at the forum as well as offering private meetings with its team of specialists. Mr Noguchi, Technology Executive with the System LSI Division of Toshiba Semiconductor Company, will present a keynote address during the Forum's conference sessions.

Visitors to the Toshiba booth will be able to find out more about the processes, methodologies and support that the TEE ASIC & Foundry business unit can provide for companies looking to develop advanced system-on-chip (SoC) technologies. The company is also offering visitors the opportunity to pre-arrange one-on-one meetings with ASIC & Foundry specialists in a private conference room. Mr Noguchi's keynote address - 'Are ASIC's Really on the Decline? The ASIC Model: Future Directions' - will take place on 3rd June at 11.15am.

To see the TEE official GSA & IET International Semiconductor Forum invitation, and to find out more about the ASIC & Foundry business, visit www.toshiba-components.com/ASIC. To register interest in arranging a private a meeting with ASIC & Foundry specialists during the exhibition e-mail GSA2009@tee.toshiba.de.

The TEE ASIC & Foundry Business Unit's open and advanced Integrated Device Manufacturer (IDM) model allows customers to speed development and reduce risk by choosing a single partner for design, implementation, production and full-service supply chain management. The company offers a wide range of leading edge CMOS solutions – including 65nm and 40nm processes and 130/65nm RFCMOS technologies - based on Toshiba's own process developments. Customised SoC development is supported through a broad lineup of production-ready, silicon-proven mixed-signal Intellectual Property (IP), including in-house and third party options.

To speed and simplify the implementation of SoCs based on the company's advanced CMOS processes, Toshiba offers a variety of development handover models in addition to full ASIC development. Hybrid models allow customers to develop mixed-signal IP

development and use Toshiba's chip-level integration, while COT (customer own tooling) models allow for physical data handover (GDSII) by the customer.

In each handover model, engineers at Toshiba's local European Design and Engineering Center (ELDEC) can provide local competence and support. ELDEC engineers have many years of experience in EDA, analogue development and design, implementation and layout. In addition, short development Turn-Around-Time (TAT) and low risk is assured thanks to flexible SoC design methodologies, optimised factory processes and professional project management.

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About Toshiba

Toshiba Electronics Europe (TEE) is the European Headquarters for the electronic components business of Toshiba Corporation, which is the world's fourth largest semiconductor vendor according to estimates by Dataquest.

Providing design, manufacturing, marketing and sales, TEE was formed in 1973 in Neuss, Germany. The company now has headquarters in Düsseldorf, Germany and subsidiaries in France, Italy, Spain, Sweden and the United Kingdom. Company president is Mr. Hitoshi Otsuka and the total number of personnel in Europe is around 400.

Toshiba Electronics Europe offers one of the industry's broadest IC and discrete product lines including high-end memory, microcontrollers, ASICs, ASSPs and display products for automotive, multimedia, consumer, telecoms and networking applications. The company also has a wide range of power semiconductor solutions.

Toshiba Corporation is a leader in information and communications systems, electronic components, consumer products and power systems. The company's integration of these wide-ranging capabilities assures its position as an innovator in advanced components, products and systems. Toshiba operates a global network of more than 740 companies, with 198,000 employees worldwide and annual sales surpassing US\$76 billion.

For more company information visit Toshiba's web site at www.toshiba-components.com

Contact details for publication:

Toshiba Electronics Europe, Hansaallee 181, D-40549 Düsseldorf, Germany

Tel: +49 (0) 211 5296 0 Fax: +49 (0) 211 5296 792197

Web: <http://www.toshiba-components.com/pressoffice/index.asp>

E-mail: CustomSOC@toshiba-components.com

Contact details for editorial enquiries:

Henning Rausch, Toshiba Electronics Europe

Tel: +49 (211) 5296 117

E-mail: HRausch@tee.toshiba.de

TEE ASIC & Foundry press contacts at GSA & IET International Semiconductor Forum:

Eugen Pfumfel

Tel: +49 (0)172 2121965

E-mail: EPfumfel@tee.toshiba.de

Issued by:

Simon Flatt/Andrew Town, Pinnacle Marketing Communications Ltd, Prosperity House, Dawlish Drive, Pinner, Middlesex, HA5 5LN, UK

Tel: +44 (0) 20 8869 9229/+44 (0) 20 8429 6546 Fax: +44 (0) 20 8868 4373.

Web: www.pinnacle-marketing.com

E-mail: simon@pinnaclemarcom.com or andrew@pinnaclemarcom.com

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